

MA2Z001

Silicon epitaxial planar type

For switching circuits

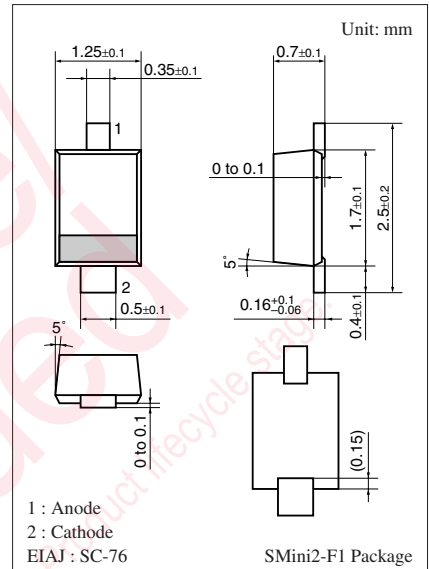
■ Features

- High breakdown voltage: $V_R = 200$ V
- Small terminal capacitance C_t
- Suitable for high-density mounting

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	200	V
Repetitive peak reverse voltage	V_{RRM}	250	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Repetitive peak forward current	I_{FRM}	225	mA
Non-repetitive peak forward surge current *	I_{FSM}	500	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $t = 1$ s



Marking Symbol: 1K

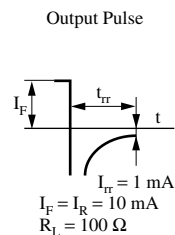
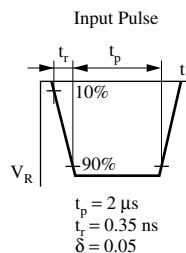
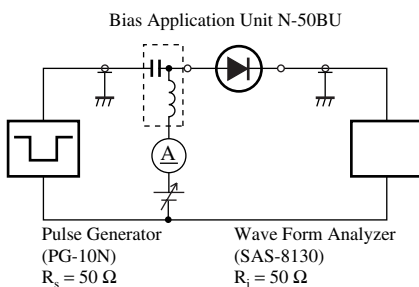
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA			1.2	V
Reverse current	I_R	$V_R = 200$ V			1.0	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz			3.0	pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 10$ mA $I_{rr} = 1$ mA, $R_L = 100$ Ω			60	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.

2. Absolute frequency of input and output is 20 MHz.

3. *: t_{rr} measurement circuit



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